

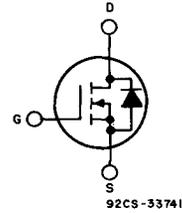
N-Channel Enhancement-Mode Power Field-Effect Transistors

12 A, 80 and 100 V

$r_{DS(on)}$: 0.2 Ω

Features:

- SOA is power-dissipation limited
- Nanosecond switching speeds
- Linear transfer characteristics
- High input impedance
- Majority carrier device



N-CHANNEL ENHANCEMENT MODE

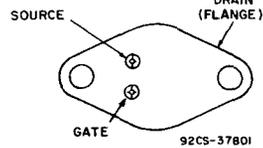
The RFM12N08 and RFM12N10 and the RFP12N08 and RFP12N10 are n-channel enhancement-mode silicon-gate power field-effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

The RFM-series types are supplied in the JEDEC TO-204AA steel package and the RFP-series types in the JEDEC TO-220AB plastic package.

The RFM and RFP series were formerly RCA developmental numbers TA9284 and TA9285.

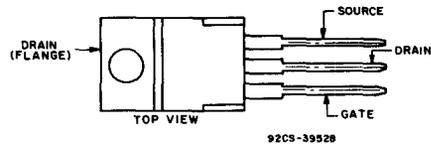
TERMINAL DESIGNATIONS

**RFM12N08
RFM12N10**



JEDEC TO-204AA

**RFP12N08
RFP12N10**



JEDEC TO-220AB

MAXIMUM RATINGS, Absolute-Maximum Values ($T_c=25^\circ\text{C}$):

	RFM12N08	RFM12N10		RFP12N08	RFP12N10	
DRAIN-SOURCE VOLTAGE V_{DSS}	80	100		80	100	V
DRAIN-GATE VOLTAGE ($R_{GS}=1\text{ M}\Omega$) ... V_{DGR}	80	100		80	100	V
GATE-SOURCE VOLTAGE V_{GS}	_____ ± 20			_____		V
DRAIN CURRENT, RMS Continuous I_D	_____ 12			_____		A
Pulsed I_{DM}	_____ 30			_____		A
POWER DISSIPATION @ $T_c=25^\circ\text{C}$ P_T	75	75		60	60	W
Derate above $T_c=25^\circ\text{C}$	0.6	0.6		0.48	0.48	W/ $^\circ\text{C}$
OPERATING AND STORAGE						
TEMPERATURE T_J, T_{stg}	_____ -55 to +150			_____		$^\circ\text{C}$

RFM12N08, RFM12N10, RFP12N08, RFP12N10

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ELECTRICAL CHARACTERISTICS, At Case Temperature (T_c)=25°C unless otherwise specified

CHARACTERISTIC	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFM12N08 RFP12N08		RFM12N10 RFP12N10		
			Min.	Max.	Min.	Max.	
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=1\text{ mA}$ $V_{GS}=0$	80	—	100	—	V
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}$ $I_D=1\text{ mA}$	2	4	2	4	V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS}=65\text{ V}$ $V_{GS}=80\text{ V}$	—	1	—	—	μA
		$T_c=125^\circ\text{ C}$ $V_{DS}=65\text{ V}$ $V_{GS}=80\text{ V}$	—	50	—	50	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20\text{ V}$ $V_{DS}=0$	—	100	—	100	nA
Drain-Source On Voltage	$V_{DS(on)}^a$	$I_D=6\text{ A}$ $V_{GS}=10\text{ V}$	—	1.2	—	1.2	V
		$I_D=12\text{ A}$ $V_{GS}=10\text{ V}$	—	3.3	—	3.3	
Static Drain-Source On Resistance	$r_{DS(on)}^a$	$I_D=6\text{ A}$ $V_{GS}=10\text{ V}$	—	0.2	—	0.2	Ω
Forward Transconductance	g_{fs}^a	$V_{DS}=10\text{ V}$ $I_D=6\text{ A}$	2	—	2	—	mho
Input Capacitance	C_{iss}	$V_{DS}=25\text{ V}$ $V_{GS}=0\text{ V}$	—	850	—	850	pF
Output Capacitance	C_{oss}	$f = 1\text{ MHz}$	—	300	—	300	
Reverse-Transfer Capacitance	C_{rss}		—	150	—	150	
Turn-On Delay Time	$t_d(on)$	$V_{DD}=50\text{ V}$ $I_D=6\text{ A}$	45(Typ)	70	45(Typ)	70	ns
Rise Time	t_r	$R_{\theta en}=R_{\theta gs}=50\ \Omega$	250(Typ)	375	250(Typ)	375	
Turn-Off Delay Time	$t_d(off)$		85(Typ)	130	85(Typ)	130	
Fall Time	t_f	$V_{GS}=10\text{ V}$	100(Typ)	150	100(Typ)	150	
Thermal Resistance Junction-to-Case	$R_{\theta jc}$	RFM12N08, RFM12N10	—	1.67	—	1.67	$^\circ\text{C/W}$
		RFP12N08, RFP12N10	—	2.083	—	2.083	

^aPulsed: Pulse duration=300 μs max., duty cycle=2%.

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFM12N08 RFM12N10		RFP12N08 RFP12N10		
			MIN.	MAX.	MIN.	MAX.	
Diode Forward Voltage	V_{SD}	$I_{SD}=6\text{ A}$	—	1.4	—	1.4	V
Reverse Recovery Time	t_{rr}	$I_F=4\text{ A}$ $dI_F/dt=100\text{ A}/\mu\text{s}$	150(typ)		150(typ)		ns

^{*}Pulse Test: Width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.

RFM12N08, RFM12N10, RFP12N08, RFP12N10

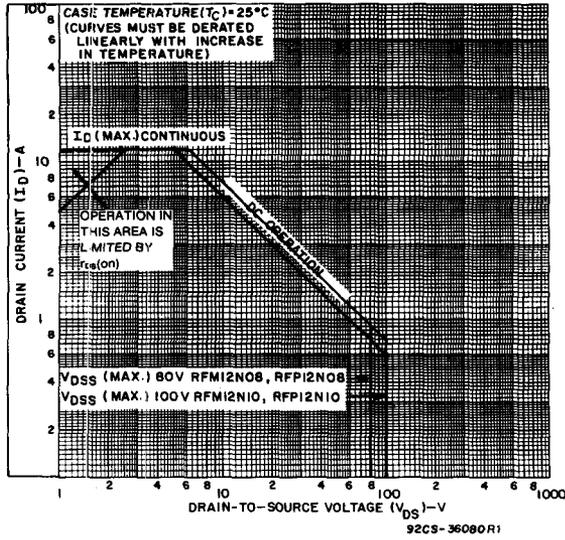


Fig. 1 - Maximum operating areas for all types.

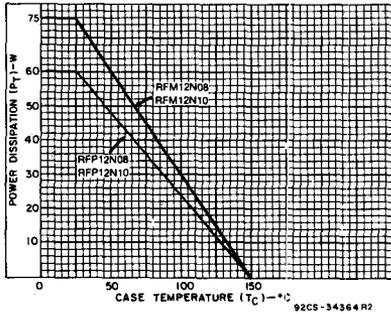


Fig. 2 - Power dissipation vs. temperature derating curve for all types.

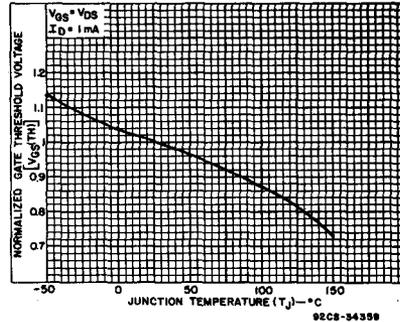


Fig. 3 - Typical normalized gate threshold voltage as a function of junction temperature for all types.

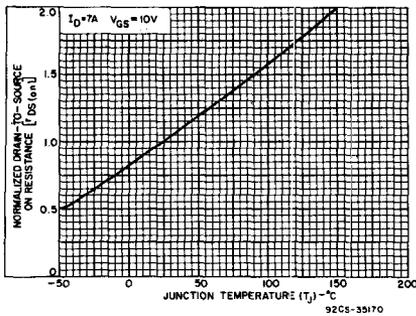


Fig. 4 - Normalized drain-to-source on resistance to junction temperature for all types.

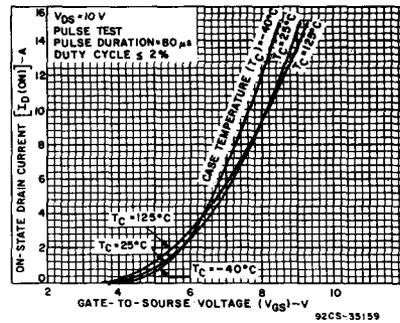


Fig. 5 - Typical transfer characteristics for all types.

RFM12N08, RFM12N10, RFP12N08, RFP12N10

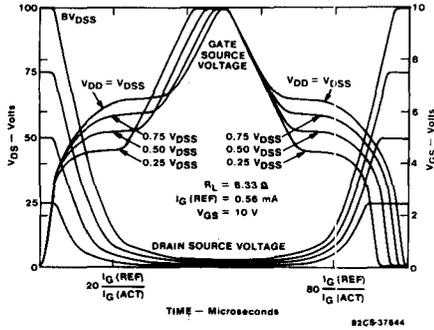


Fig. 6 - Normalized switching waveforms for constant gate-current. Refer to RCA application notes AN-7254 and AN-7260.

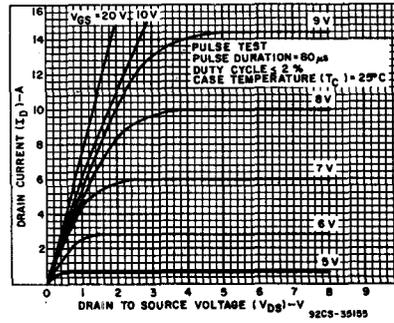


Fig. 7 - Typical saturation characteristics for all types.

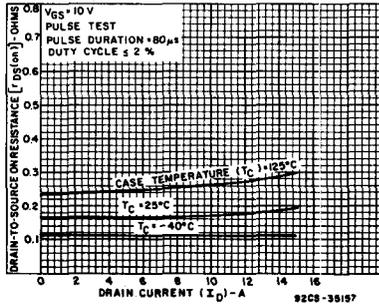


Fig. 8 - Typical drain-to-source on resistance as a function of drain current for all types.

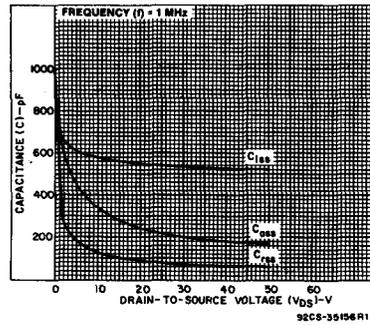


Fig. 9 - Capacitance as a function of drain-to-source voltage for all types.

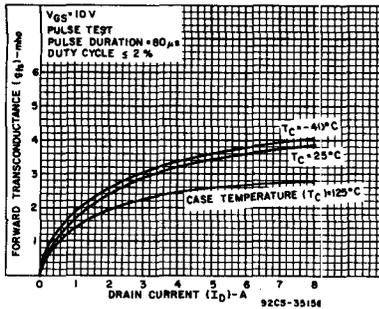


Fig. 10 - Typical forward transconductance as a function of drain current for all types.

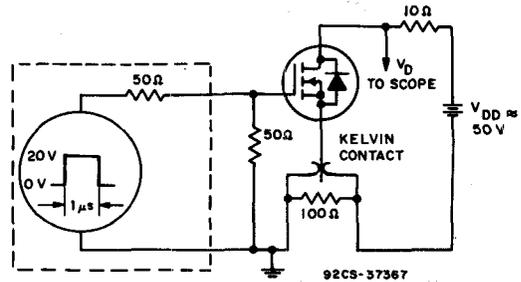


Fig. 11 - Switching Time Test Circuit

RFM12N18, RFM12N20, RFP12N18, RFP12N20

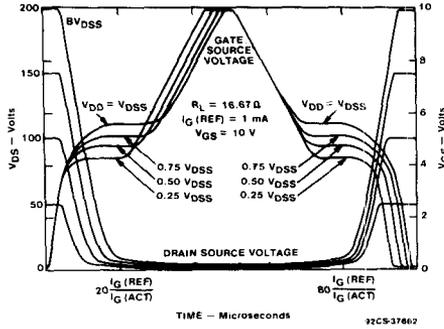


Fig. 6 - Normalized switching waveforms for constant gate-current. Refer to RCA application notes AN-7254 and AN-7260.

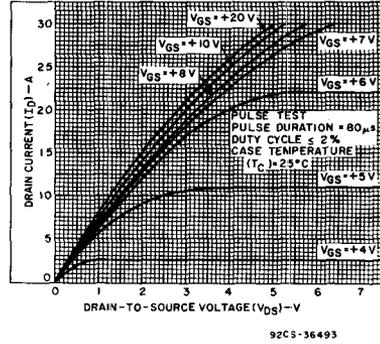


Fig. 7 - Typical saturation characteristics for all types.

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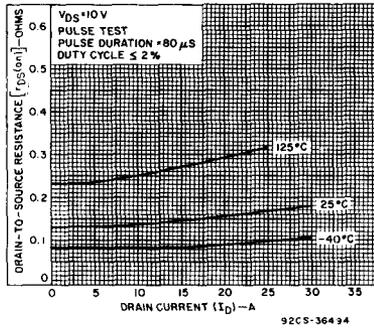


Fig. 8 - Typical drain-to-source on resistance as a function of drain current for all types.

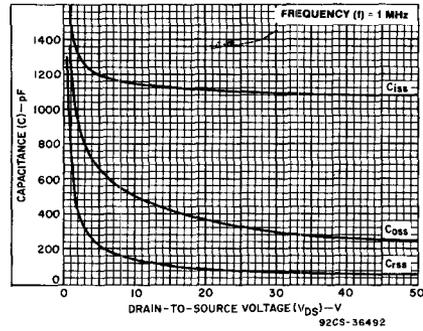


Fig. 9 - Capacitance as a function of drain-to-source voltage for all types.

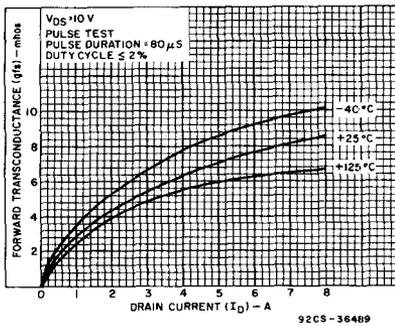


Fig. 10 - Typical forward transconductance as a function of drain current for all types.

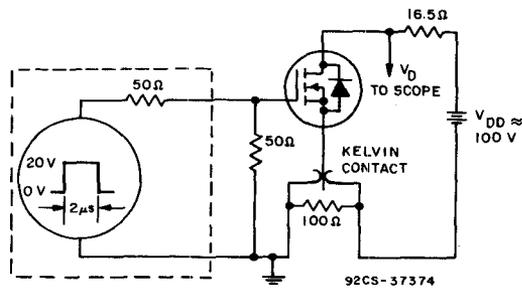


Fig. 11 - Switching Time Test Circuit